

DELIVERY SPECIFICATION

SPEC. No. A-LMEGA-C-b  
D A T E : Sep., 2024

To

Non-Controlled Copy

CUSTOMER'S PRODUCT NAME	TDK PRODUCT NAME Multilayer Ceramic Chip Capacitors (Mega cap CA series) Tape packaging 【RoHS2 compliant】 CAA572,CAA573 type C0G Characteristics
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Please return this specification to TDK representatives with your signature.  
If orders are placed without returned specification, please allow us to judge that specification is accepted by your side.

RECEIPT CONFIRMATION

DATE:                      YEAR                      MONTH                      DAY

Test conditions in this specification based on AEC-Q200 for automotive application.

TDK Corporation  
Sales  
Electronic Components  
Sales & Marketing Group

Engineering  
Electronic Components Business Company  
Ceramic Capacitors Business Group

APPROVED	Person in charge	APPROVED	CHECKED	Person in charge

**SCOPE**

This delivery specification shall be applied to Multilayer ceramic chip capacitors (Mega cap CA series) to be delivered to \_\_\_\_\_.

**PRODUCTION PLACES**

Production places defined in this specification shall be TDK Corporation, TDK Xiamen Co.,Ltd, TDK(Suzhou)Co.,Ltd and TDK Components U.S.A.Inc.

**PRODUCT NAME**

The name of the product to be defined in this specifications shall be CAA57◇○○○△△□□□×.

**REFERENCE STANDARD**

JIS C 5101 – 1 : 2010	Fixed capacitors for use in electronic equipment-Part 1: Generic specification
C 5101 – 21 : 2014	Fixed capacitors for use in electronic equipment-Part 21 : Sectional specification : Fixed surface mount multilayer capacitors of ceramic dielectric,Class1
C 0806 – 3 : 2014	Packaging of components for automatic handling - Part 3 : Packaging of surface mount components on continuous tapes
JEITA RCR – 2335 C 2014	Safety application guide for fixed ceramic capacitors for use in electronic equipment

**CONTENTS**

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11. TAPE PACKAGING SPECIFICATION

**EXPLANATORY NOTE**

When the mistrust in the spec arises, this specification is given priority. And it will be confirmed by written spec change after conference of both posts involved.

This specification warrants the quality of the ceramic chip capacitor. Capacitors should be evaluated or confirmed a state of mounted on your product.

If the use of the capacitors goes beyond the bounds of this specification, we can not afford to guarantee.

Division	Date	SPEC. No.
Ceramic Capacitors Business Group	Sep., 2024	A-LMEGA-C-b

## 1. CODE CONSTRUCTION

(Example)	CA	A	57	2	C0G	3A	303	J	T	OOOO
	<u>CA</u>	<u>A</u>	<u>57</u>	<u>3</u>	<u>C0G</u>	<u>2J</u>	<u>304</u>	<u>J</u>	<u>T</u>	<u>OOOO</u>
	(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)	(10)

(1) Series

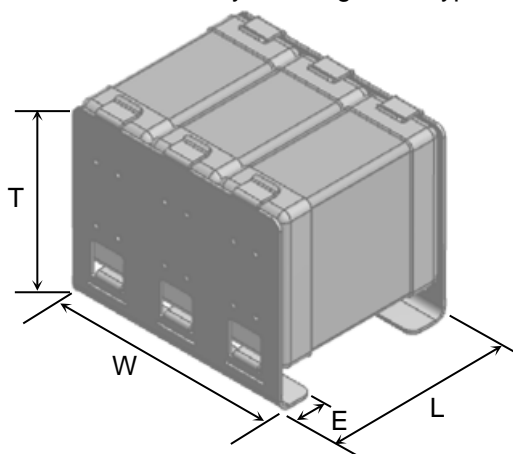
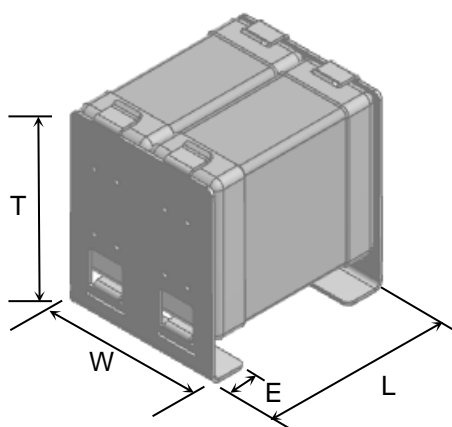
Symbol	Series
CA	Mega cap CA series

(2) TDK's auxiliary code

(3) Type

CAA572 : 2 side-by-side alignment type

CAA573 : 3 side-by-side alignment type



Type	Structure Symbol	Dimensions (Unit : mm)			
		L	W	T	E
57	2	6.00±0.50	5.60±0.50	6.40±0.50	1.20±0.20
57	3	6.00±0.50	8.40±0.50	6.40±0.50	1.20±0.20

\*As for each item, please refer to detail page on TDK web.

(4) Structure

Symbol	Structure
2	2 side-by-side alignment type
3	3 side-by-side alignment type

(5) Temperature Characteristics

Symbol	Temperature Characteristics
C0G	0 ± 30 ppm/°C (-55 ~ 125°C)

(6) Rated Voltage

Symbol	Rated Voltage
3 A	DC 1 kV
2 J	DC 630 V

## (7) Rated Capacitance

Stated in three digits and in units of pico farads (pF).

The first and second digits identify the first and second significant figures of the Capacitance, the third digit identifies the multiplier.

(Example)

Symbol	Rated Capacitance
303	30,000 pF
304	300,000 pF

## (8) Capacitance tolerance

Symbol	Tolerance
J	± 5 %

## (9) Packaging

Symbol	Packaging
T	Taping

## (10) TDK internal code

**2. OPERATING TEMPERATURE RANGE**

Min. operating Temperature	Max. operating Temperature	Reference Temperature
-55°C	125°C	25°C

**3. STORING CONDITION AND TERM**

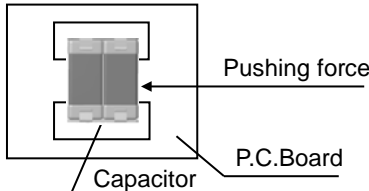
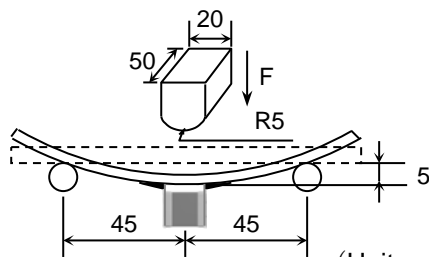
Storing temperature	Storing humidity	Storing term
5~40°C	20~70%RH	Within 6 months upon receipt.

**4. INDUSTRIAL WASTE DISPOSAL**

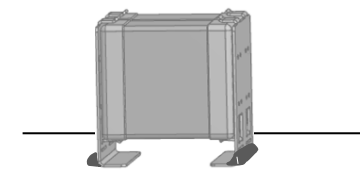
Dispose this product as industrial waste in accordance with the Industrial Waste Law.

## 5. PERFORMANCE

Table 1

No.	Item		Performance	Test or inspection method						
1	External Appearance		No defects which may affect performance.	Inspect with magnifying glass(3×)						
2	Insulation Resistance		10,000MΩ or 500MΩ・μF min., whichever smaller.	Measuring voltage : DC500V Voltage application time : 60s.						
3	Voltage Proof		Withstand test voltage without insulation breakdown or other damage.	<table><tr><td>Rated voltage(RV)</td><td>Apply voltage</td></tr><tr><td>DC630V</td><td>1.3 × rated voltage</td></tr><tr><td>DC1kV</td><td>1.2 × rated voltage</td></tr></table> Voltage application time : 1s. Charge / discharge current : 50mA or lower	Rated voltage(RV)	Apply voltage	DC630V	1.3 × rated voltage	DC1kV	1.2 × rated voltage
Rated voltage(RV)	Apply voltage									
DC630V	1.3 × rated voltage									
DC1kV	1.2 × rated voltage									
4	Capacitance		Within the specified tolerance.	<table><tr><td>Measuring frequency</td><td>Measuring voltage</td></tr><tr><td>1kHz±10%</td><td>0.5 ~ 5V rms.</td></tr></table>	Measuring frequency	Measuring voltage	1kHz±10%	0.5 ~ 5V rms.		
Measuring frequency	Measuring voltage									
1kHz±10%	0.5 ~ 5V rms.									
5	Q		Please refer to detail page on TDK web.	See No.4 in this table for measuring condition.						
6	Temperature Characteristics of Capacitance		<table><tr><td>T.C.</td><td>Temperature Coefficient (ppm/°C)</td></tr><tr><td>C0G</td><td>0 ± 30</td></tr></table> <table><tr><td>Capacitance drift</td><td>Within ± 0.2%</td></tr></table>	T.C.	Temperature Coefficient (ppm/°C)	C0G	0 ± 30	Capacitance drift	Within ± 0.2%	Temperature coefficient shall be calculated based on values at 25°C and 85°C temperature.  Measuring temperature below 25°C shall be -10°C and -25°C.
T.C.	Temperature Coefficient (ppm/°C)									
C0G	0 ± 30									
Capacitance drift	Within ± 0.2%									
7	Robustness of Terminations		No sign of termination coming off, breakage of ceramic, or other abnormal signs.	Reflow solder the capacitors on a P.C.Board shown in Appendix 2. Apply a pushing force gradually at the center of a specimen in a horizontal direction of P.C.board. Pushing force : 17.7N Holding time : 10±1s 						
8	Bending	External appearance	No mechanical damage.	Reflow solder the capacitor on a P.C.Board shown in Appendix1.  (Unit : mm)						

(continued)

No.	Item		Performance		Test or inspection method															
9	Solderability		Both end faces and the contact areas shall be covered with a smooth and bright solder coating with no more than a small amount of scattered imperfections such as pinholes or un-wetted or de-wetted areas. These imperfections shall not be concentrated in one area. <div></div>		Solder : Sn-3.0Ag-0.5Cu  Reflow solder the capacitor on a P.C.Board shown in Appendix2.  Please refer to No.5 Soldering in 10.CAUTION for soldering condition.															
10	Vibration	External appearance	No mechanical damage.		Applied force : 5G max. Frequency : 10~2,000Hz Reciprocating sweep time : 20 min. Cycle : 12 cycles in each 3 mutually perpendicular directions.  Reflow solder the capacitors on a P.C.Board shown in Appendix 2 before testing.															
		Capacitance	Characteristic s	Change from the value before test																
			C0G	± 2.5 %																
		Q	1,000 min.																	
11	Temperature Cycle	External appearance	No mechanical damage.		Expose the capacitors in the condition step1 through step 4 listed in the following table.  Temp. cycle : 1,000 cycles <table><tr><td>Step</td><td>Temperature(°C)</td><td>Time(min.)</td></tr><tr><td>1</td><td>-55 ± 3</td><td>30±3</td></tr><tr><td>2</td><td>Ambient Temp.</td><td>2 ~ 5</td></tr><tr><td>3</td><td>125 ± 2</td><td>30±2</td></tr><tr><td>4</td><td>Ambient Temp.</td><td>2 ~ 5</td></tr></table>  Leave the capacitors in ambient condition for 6~24h before measurement.  Reflow solder the capacitors on a P.C.Board shown in Appendix2 before testing.	Step	Temperature(°C)	Time(min.)	1	-55 ± 3	30±3	2	Ambient Temp.	2 ~ 5	3	125 ± 2	30±2	4	Ambient Temp.	2 ~ 5
		Step	Temperature(°C)	Time(min.)																
		1	-55 ± 3	30±3																
		2	Ambient Temp.	2 ~ 5																
		3	125 ± 2	30±2																
		4	Ambient Temp.	2 ~ 5																
Capacitance	Characteristic s	Change from the value before test																		
	C0G	Please contact with our sales representative.																		
Q	1,000 min.																			
Insulation Resistance	Meet the initial spec.																			
Voltage proof	No insulation breakdown or other damage.																			

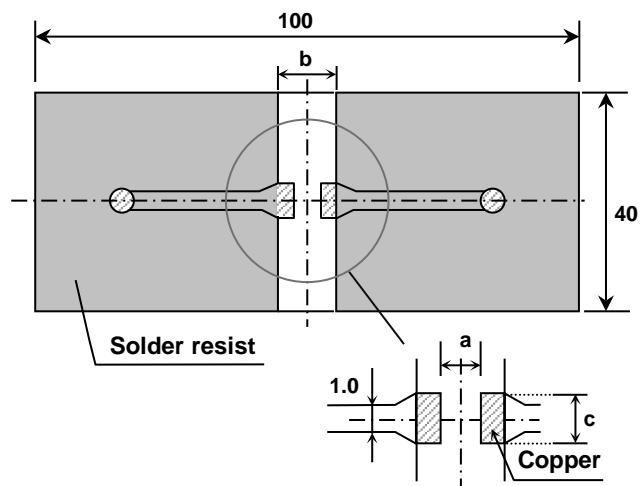
(continued)

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No.	Item		Performance		Test or inspection method
12	Moisture Resistance	External appearance	No mechanical damage.		Test temp. : 85±2°C Test humidity : 85%RH Applied voltage : Rated voltage Test time : 1,000 +48,0h Charge/discharge current : 50mA or lower Leave the capacitors in ambient condition for 6~24h before measurement.  Reflow solder the capacitors on a P.C.Board shown in Appendix2 before testing.
		Capacitance	Characteristics	Change from the value before test	
			C0G	Please contact with our sales representative.	
			Q	200 min.	
		Insulation Resistance	500MΩ or 25MΩ · μF min., whichever smaller.		
13	Life	External appearance	No mechanical damage.		Test temp. : 125±2°C Applied voltage : Please contact with our sales representative. Test time : 1,000 +48,0h  Charge/discharge current : 50mA or lower  Leave the capacitors in ambient condition for 6~24h before measurement.  Reflow solder the capacitors on a P.C.Board shown in Appendix2 before testing.
		Capacitance	Characteristics	Change from the value before test	
			C0G	Please contact with our sales representative.	
			Q	350 min.	
		Insulation Resistance	1,000MΩ or 50MΩ · μF min., whichever smaller.		

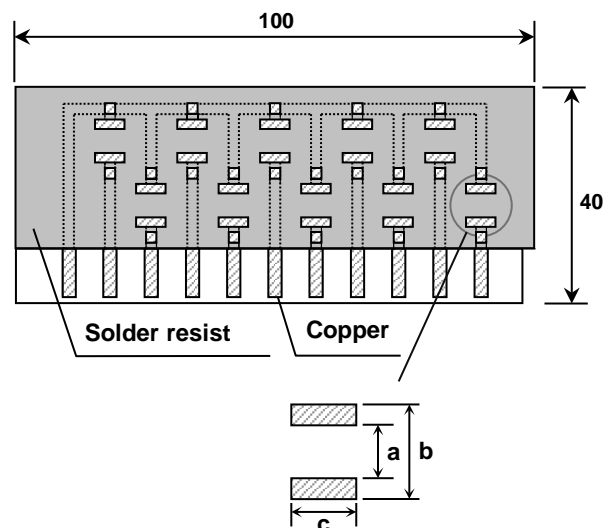
## Appendix 1

## P.C.Board for bending test



## Appendix 2

## P.C. Board for reliability test

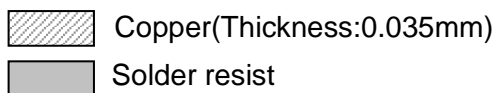


(Unit : mm)

Symbol Case size	Dimensions		
	a	b	c
CAA572	4.5	8.0	5.6
CAA573	4.5	8.0	8.1

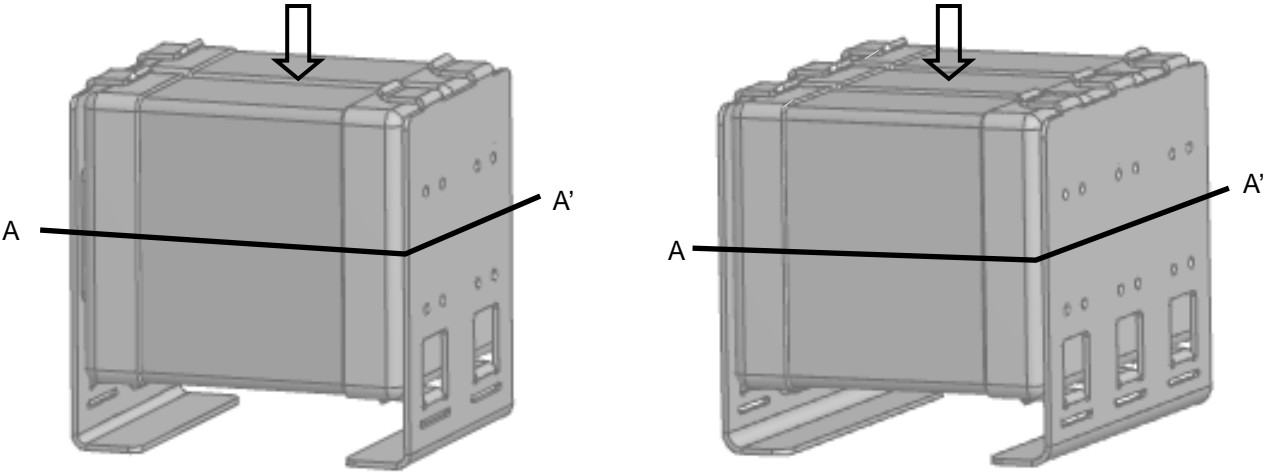
1. Material : Glass Epoxy(As per JIS C6484 GE4)

2. Thickness : 1.6mm

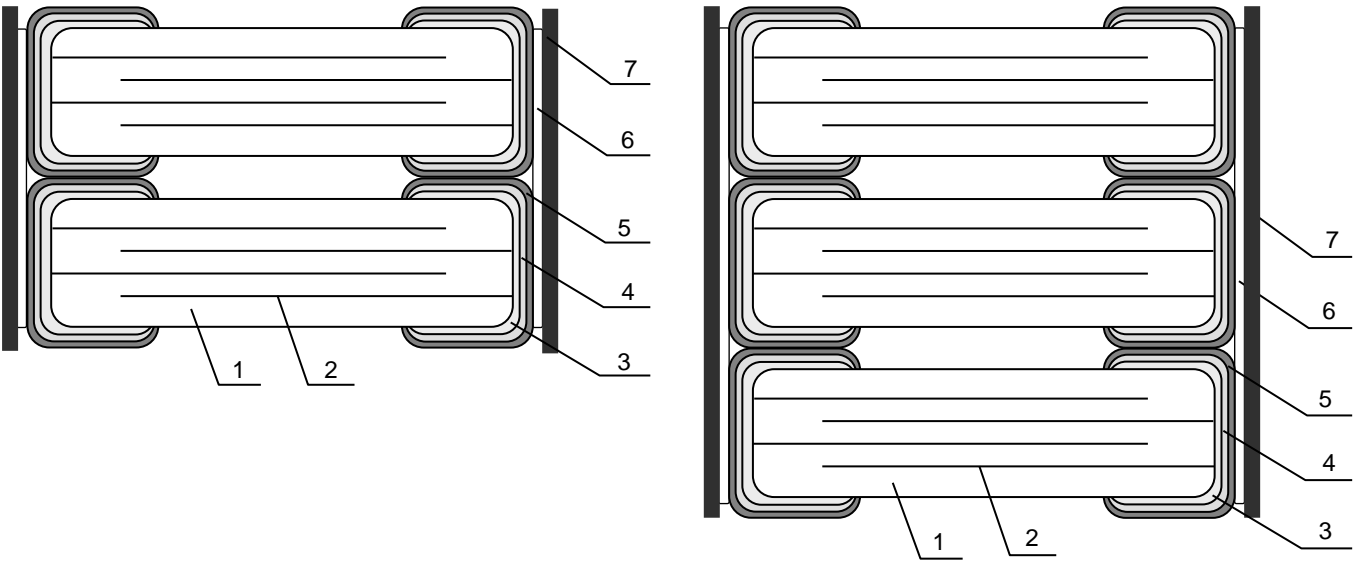




6. INSIDE STRUCTURE AND MATERIAL



A—A'



No.	NAME	MATERIAL
1	Dielectric	CaZrO <sub>3</sub>
2	Electrode	Nickel (Ni)
3	Termination	Copper (Cu)
4		Nickel (Ni)
5		Tin (Sn)
6	Metal cap joint	High temp solder
7	Metal cap	Clad

## 7. PACKAGING

Packaging shall be done to protect the components from the damage during transportation and storing, and a label which has the following information shall be attached.

Tape packaging is as per 11. TAPE PACKAGING SPECIFICATION.

- 1) Inspection No.
- 2) TDK P/N
- 3) Customer's P/N
- 4) Quantity

\*Composition of Inspection No.

Example      E 4 A - 23 - 001  
                   (a) (b) (c)        (d)        (e)

- a) Line code
- b) Last digit of the year
- c) Month and A for January and B for February and so on. (Skip I)
- d) Inspection Date of the month.
- e) Serial No. of the day

\*Composition of new Inspection No.

(Will be implemented on and after May. 1, 2019)

Example      

I	F	4	E	2	3	A	0	0	1
(a)	(b)	(c)	(d)	(e)		(f)		(g)	

- (a) Prefix
- (b) Line code
- (c) Last digit of the year
- (d) Month and A for January and B for February and so on. (Skip I)
- (e) Inspection Date of the month.
- (f) Serial No. of the day(00 ~ ZZ)
- (g) Suffix(00 ~ ZZ)

\* It was shifted to the new inspection No. on and after May 2019, but the implementation timing may be different depending on shipment bases. Until the shift is completed, either current or new composition of inspection No. will be applied.

## 8. RECOMMENDATION

It is recommended to provide a slit (about 1mm wide) in the board under the components to improve washing Flux.


And please make sure to dry detergent up completely before.

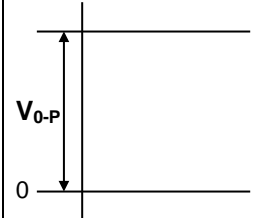
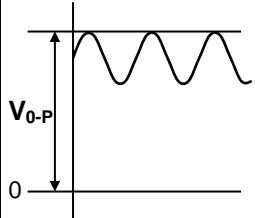
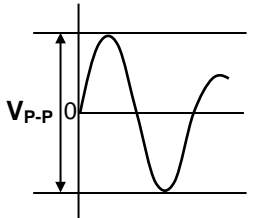
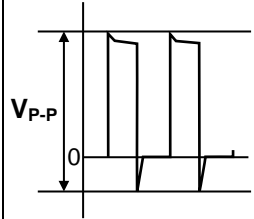
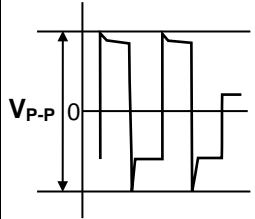
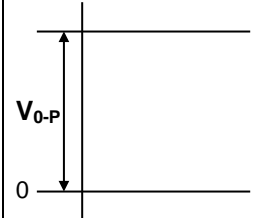
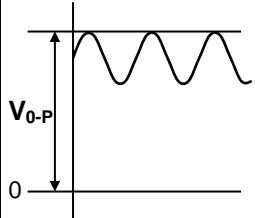
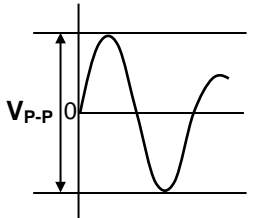
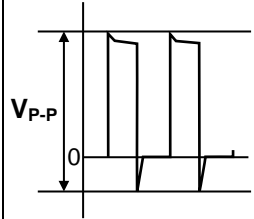
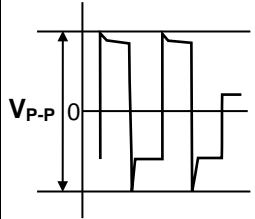
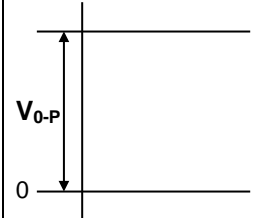
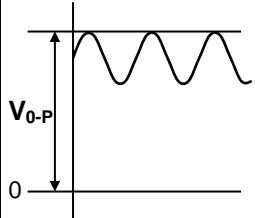
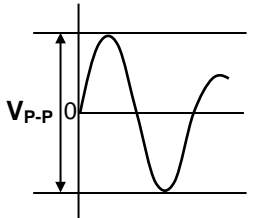
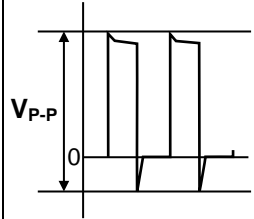
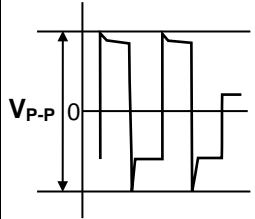
## 9. SOLDERING CONDITION

Reflow soldering only.

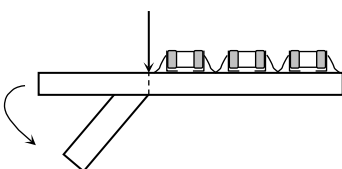
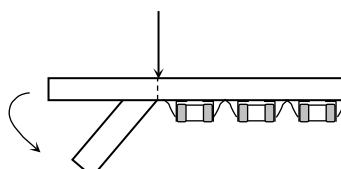
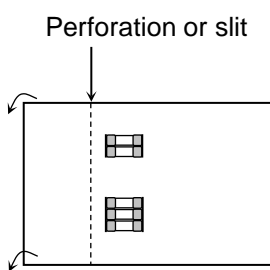
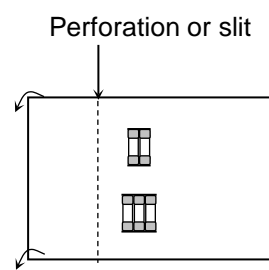
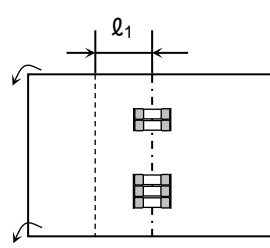
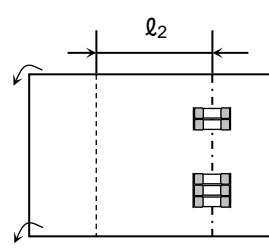
Please refer to No.5 Soldering in 10. CAUTION for recommended soldering condition.

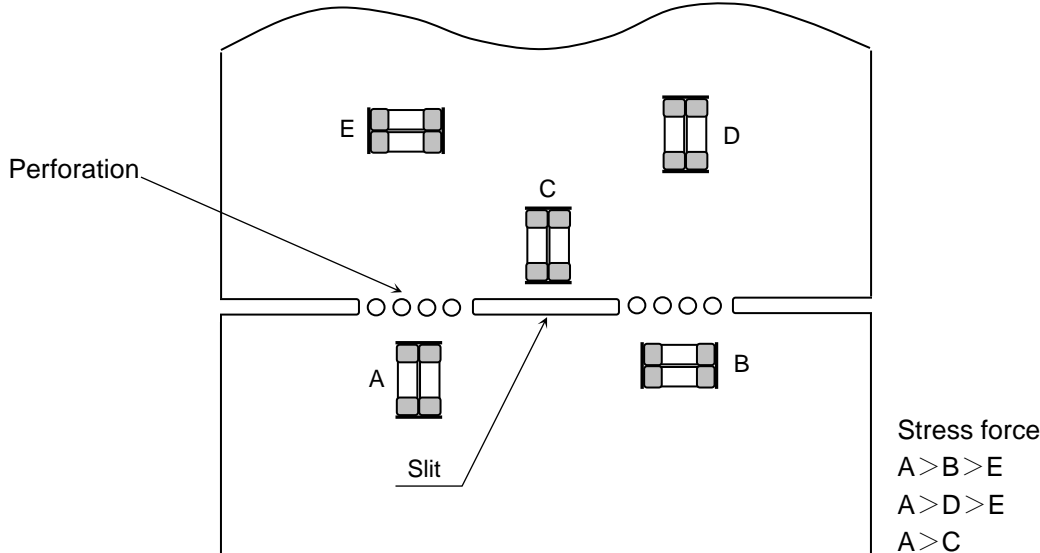
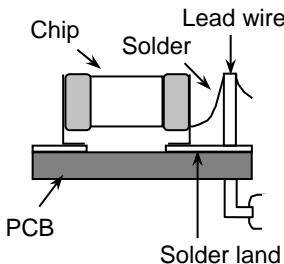
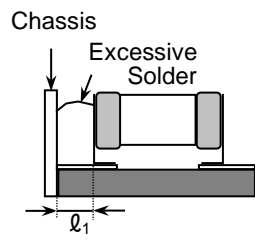
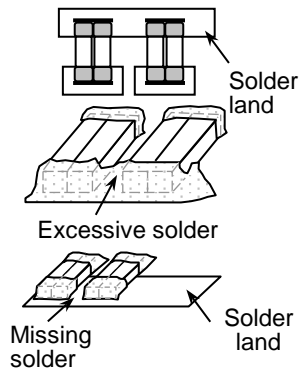
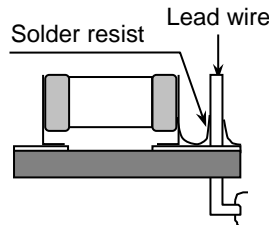
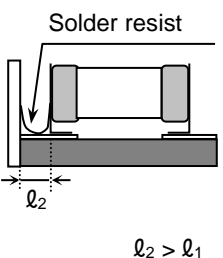
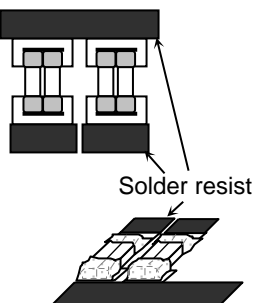
## 10. CAUTION

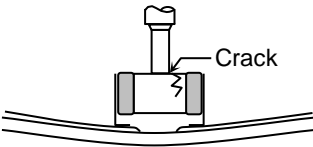
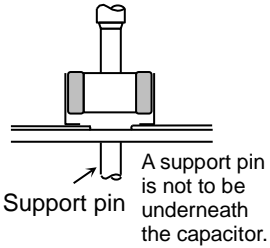
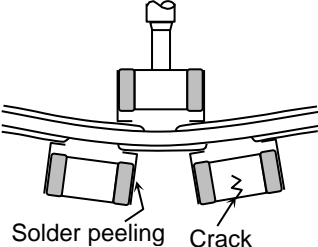
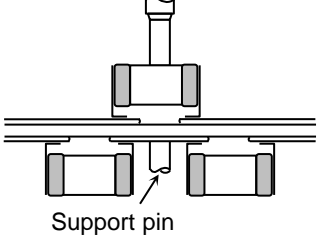
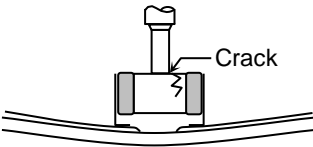
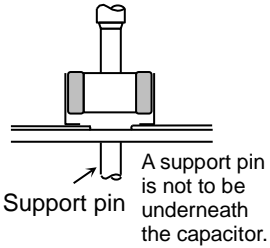
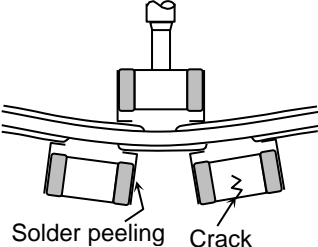
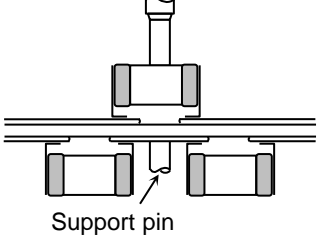
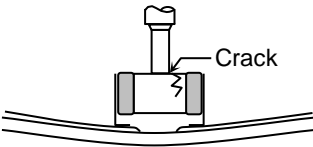
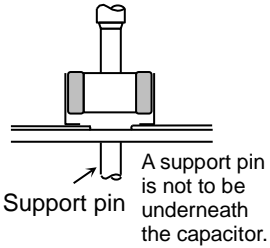
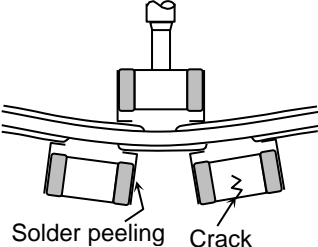
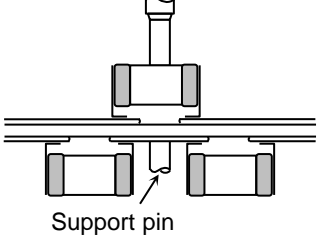
No.	Process	Condition
1	Operating Condition (Storage, Use, Transportation)	<p>1-1. Storage, Use The capacitors must be stored in an ambient temperature of 5 to 40°C with a relative humidity of 20 to 70%RH. JIS C 60721-3-1 Class 1K2 should be followed for the other climatic conditions.</p> <ol style="list-style-type: none"> <li>1) High temperature and humidity environment may affect a capacitor's solder ability because it accelerates terminal oxidization. They also deteriorate performance of taping and packaging. Therefore, SMD capacitors shall be used within 6 months. For capacitors with terminal electrodes consisting of silver or silver-palladium which tend to become oxidized or sulfurized, use as soon as possible, such as within one month after opening the bag.</li> <li>2) When capacitors are stored for a period longer than specified, confirm the solderability of the capacitors prior to use. During storage, keep the minimum packaging unit in its original packaging without opening it. Do not deviate from the above temperature and humidity conditions even for a short term.</li> <li>3) Corrosive gasses in the air or atmosphere may result in deterioration of the reliability, such as poor solderability of the terminal electrodes. Do not store capacitors where they will be exposed to corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine ammonia etc.)</li> <li>4) Solderability and electrical performance may deteriorate due to photochemical change in the terminal electrode if stored in direct sunlight, or due to condensation from rapid changes in humidity. The capacitors especially which use resin material must be operated and stored in an environment free of dew condensation, as moisture absorption due to condensation may affect the performance.</li> <li>5) Refer to JIS C 60721-3-1, class 1K2 for other climate conditions.</li> </ol> <p>1-2. Handling in transportation In case of the transportation of the capacitors, the performance of the capacitors may be deteriorated depending on the transportation condition. (Refer to JEITA RCR-2335C 9.2 Handling in transportation)</p>
2	Circuit design  Caution	<p>2-1. Operating temperature</p> <ol style="list-style-type: none"> <li>1) Upper category temperature (maximum operating temperature) is specified. It is necessary to select a capacitor whose rated temperature is higher than the operating temperature. Also, it is necessary to consider the temperature distribution in the equipment and seasonal temperature variation.</li> <li>2) Surface temperature including self heating should be below maximum operating temperature. Due to dielectric loss, capacitors will heat itself when AC is applied due to ESR. Especially at high frequencies, please be careful that the heat might be so extreme. Also, even if the surface temperature of the capacitor includes self-heating and is the maximum operating temperature or lower, excessive heating of the capacitor due to self-heating may cause deterioration of the characteristics and reliability of the capacitor. The self-heating temperature rise of the capacitor changes depending on the difference in heat radiation due to the mounting method to the device, the ambient temperature, the cooling method of the device, etc. As a guide, please consult us if the self-heating temperature rise of the capacitor in a natural convection environment at an ambient temperature of 25°C exceeds 20°C. When using in a high-frequency circuit or a circuit in which a capacitor generates heat, such as when a high-frequency ripple current flows, pay attention to the above precautions. (Note that accurate measurement may not be possible with self-heating measurement when the equipment applies cooling other than natural convection such as a cooling fan.)</li> <li>3) The electrical characteristics of the capacitors will vary depending on the temperature. The capacitors should be selected and designed in taking the temperature into consideration.</li> </ol>

No.	Process	Condition														
2	Circuit design ⚠ Caution	<p>2-2. When overvoltage is applied Applying overvoltage to a capacitor may cause dielectric breakdown and result in a short circuit. The duration until dielectric breakdown depends on the applied voltage and the ambient temperature.</p> <p>2-3. Operating voltage</p> <p>1) Operating voltage across the terminals should be below the rated voltage. When AC and DC are super imposed, <math>V_{0-P}</math> must be below the rated voltage. — (1) and (2) AC or pulse with overshooting, <math>V_{P-P}</math> must be below the rated voltage. — (3), (4) and (5)</p> <p>When the voltage is started to apply to the circuit or it is stopped applying, the irregular voltage may be generated for a transit period because of resonance or switching. Be sure to use the capacitors within rated voltage containing these Irregular voltage.</p> <table><tr><th>Voltage</th><th>(1) DC voltage</th><th>(2) DC+AC voltage</th><th>(3) AC voltage</th></tr><tr><td>Positional Measurement (Rated voltage)</td><td></td><td></td><td></td></tr></table> <table><tr><th>Voltage</th><th>(4) Pulse voltage (A)</th><th>(5) Pulse voltage (B)</th></tr><tr><td>Positional Measurement (Rated voltage)</td><td></td><td></td></tr></table> <p>2) Even below the rated voltage, if repetitive high frequency AC or pulse is applied, the reliability of the capacitors may be reduced.</p> <p>3) The effective capacitance will vary depending on applied DC and AC voltages. The capacitors should be selected and designed in taking the voltages into consideration.</p> <p>4) Abnormal voltage (surge voltage, static electricity, pulse voltage, etc.) shall not exceed the rated voltage.</p> <p>5) When capacitors are used in a series connection, it is necessary to add a balancing circuit such as voltage dividing resistors in order to avoid an imbalance in the voltage applied to each capacitor.</p>	Voltage	(1) DC voltage	(2) DC+AC voltage	(3) AC voltage	Positional Measurement (Rated voltage)				Voltage	(4) Pulse voltage (A)	(5) Pulse voltage (B)	Positional Measurement (Rated voltage)		
Voltage	(1) DC voltage	(2) DC+AC voltage	(3) AC voltage													
Positional Measurement (Rated voltage)																
Voltage	(4) Pulse voltage (A)	(5) Pulse voltage (B)														
Positional Measurement (Rated voltage)																

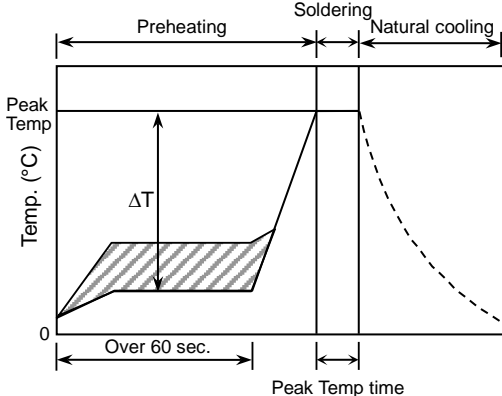
No.	Process	Condition															
3	Designing P.C.board	<p>The amount of solder at the terminations has a direct effect on the reliability of the capacitor.</p> <ol style="list-style-type: none"> <li>1) The greater the amount of solder, the higher the stress on the chip capacitor, and the more likely that it will break. When designing a P.C.board, determine the shape and size of the solder lands to have proper amount of solder on the terminations.</li> <li>2) Avoid using common solder land for multiple terminations and provide individual solder land for each terminations.</li> <li>3) Size and recommended land dimensions.</li> </ol> <div data-bbox="636 667 1353 969"> <p>The diagram illustrates the recommended dimensions for a chip capacitor on a PCB. It shows two capacitors side-by-side. Dimension 'A' is the distance between the centers of the two capacitors. Dimension 'B' is the width of the solder land for one capacitor. Dimension 'C' is the height of the solder land. Labels include 'Chip capacitors' pointing to the capacitors, 'Solder land' pointing to the area between the capacitors, and 'Solder resist' pointing to the area on the right.</p> </div> <table border="1" data-bbox="604 1064 1318 1408"> <tr> <th colspan="3">(Unit : mm)</th></tr> <tr> <th>Case size Symbol</th><th>CAA572</th><th>CAA573</th></tr> <tr> <td>A</td><td>4.3 ~ 4.7</td><td>4.3 ~ 4.7</td></tr> <tr> <td>B</td><td>1.5 ~ 2.0</td><td>1.5 ~ 2.0</td></tr> <tr> <td>C</td><td>5.2 ~ 5.7</td><td>7.9 ~ 8.4</td></tr> </table>	(Unit : mm)			Case size Symbol	CAA572	CAA573	A	4.3 ~ 4.7	4.3 ~ 4.7	B	1.5 ~ 2.0	1.5 ~ 2.0	C	5.2 ~ 5.7	7.9 ~ 8.4
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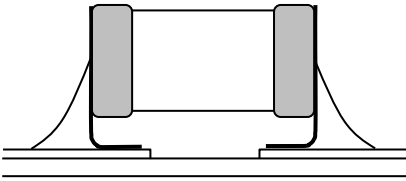
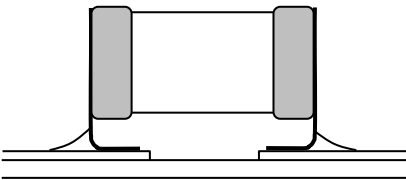
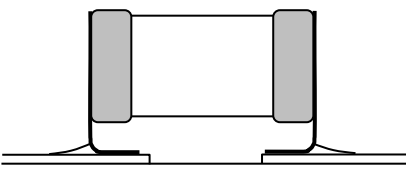
No.	Process	Condition		
3	Designing P.C.board	4) Recommended chip capacitor layout is as following.		
			Disadvantage against bending stress	Advantage against bending stress
		Mounting face	<p>Perforation or slit</p>  <p>Break P.C.board with mounted side up.</p>	<p>Perforation or slit</p>  <p>Break P.C.board with mounted side down.</p>
		Chip arrangement t (Direction)	<p>Mount perpendicularly to perforation or slit</p> <p>Perforation or slit</p> 	<p>Mount in parallel with perforation or slit</p> <p>Perforation or slit</p> 
		Distance from slit	<p>Closer to slit is higher stress</p>  <p>( <math>l_1 &lt; l_2</math> )</p>	<p>Away from slit is less stress</p>  <p>( <math>l_1 &lt; l_2</math> )</p>


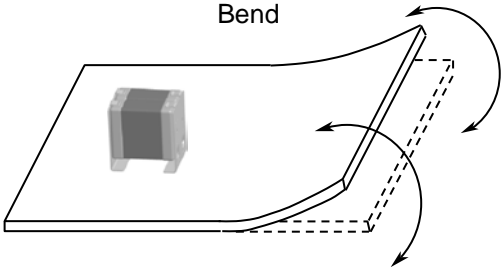
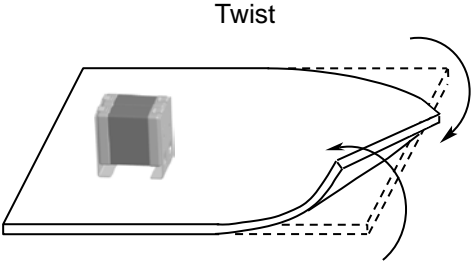
No.	Process	Condition	
3	Designing P.C.board	<div>5) Mechanical stress varies according to location of chip capacitors on the P.C.board.</div> <div><p>Stress force A &gt; B &gt; E A &gt; D &gt; E A &gt; C</p><p>When dividing printed wiring boards, the intensities of mechanical stress applied to capacitors are different according to each dividing method in the order of : Push-back &lt; Slit &lt; V-groove &lt; Perforation. Therefore consider not only position of capacitors, but also the way of the dividing the printed wiring boards.</p></div>	
6) Layout recommendation			
Example	Use of common solder land	Soldering with chassis	Use of common solder land with other SMD
Need to avoid			
Recommendation			


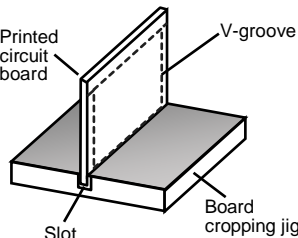
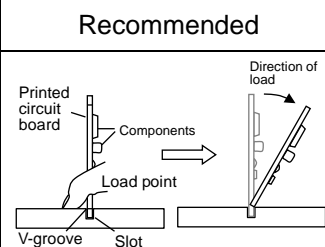
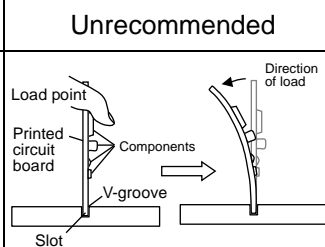
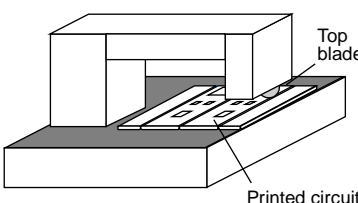
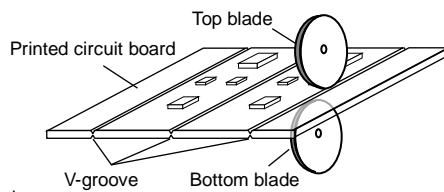
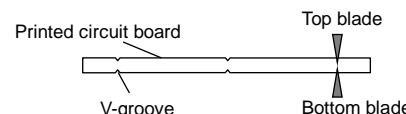
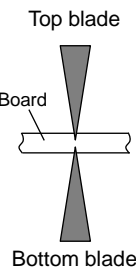
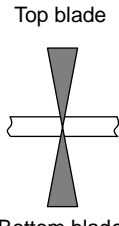
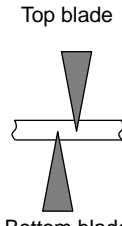
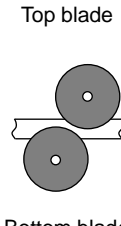
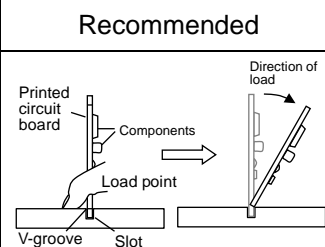
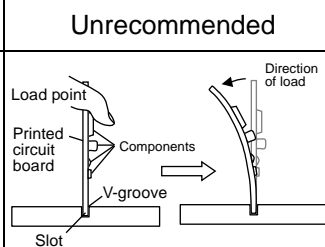
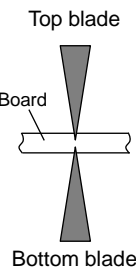
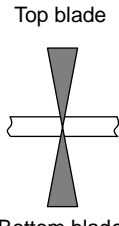
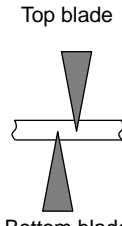
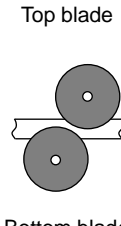
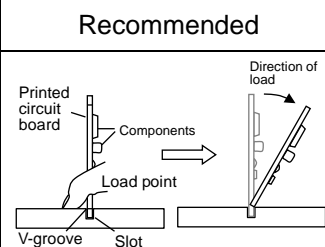
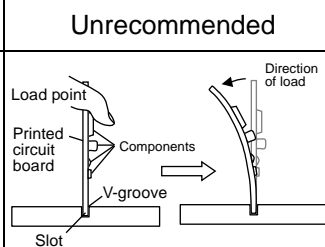
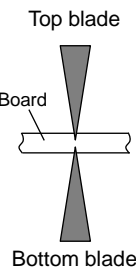
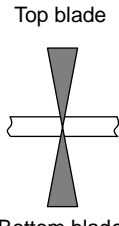
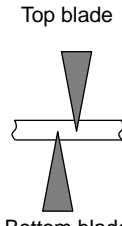
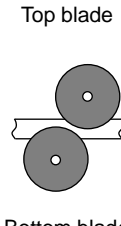
No.	Process	Condition									
4	Mounting	<p>4-1. Stress from mounting head</p> <p>If the mounting head is adjusted too low, it may induce excessive stress in the chip capacitor to result in cracking. Please take following precautions.</p> <ol style="list-style-type: none"> <li>1) Adjust the bottom dead center of the mounting head to reach on the P.C.board surface and not press it.</li> <li>2) Adjust the mounting head pressure to be 1 to 3N of static weight.</li> <li>3) To minimize the impact energy from mounting head, it is important to provide support from the bottom side of the P.C.board. See following examples.</li> </ol> <table border="1"> <thead> <tr> <th></th><th>Not recommended</th><th>Recommended</th></tr> </thead> <tbody> <tr> <td>Single sided mounting</td><td>  <p>Crack</p> </td><td>  <p>Support pin</p> <p>A support pin is not to be underneath the capacitor.</p> </td></tr> <tr> <td>Double-sides mounting</td><td>  <p>Solder peeling</p> <p>Crack</p> </td><td>  <p>Support pin</p> </td></tr> </tbody> </table> <p>When the centering jaw is worn out, it may give mechanical impact on the capacitor to cause crack. Please control the close up dimension of the centering jaw and provide sufficient preventive maintenance and replacement of it.</p>		Not recommended	Recommended	Single sided mounting	 <p>Crack</p>	 <p>Support pin</p> <p>A support pin is not to be underneath the capacitor.</p>	Double-sides mounting	 <p>Solder peeling</p> <p>Crack</p>	 <p>Support pin</p>
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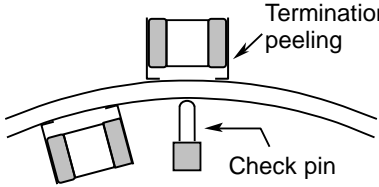
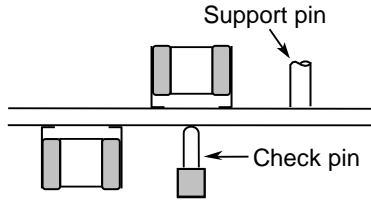
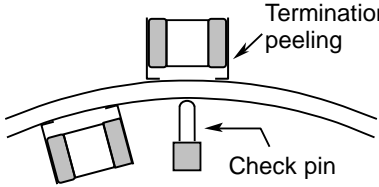
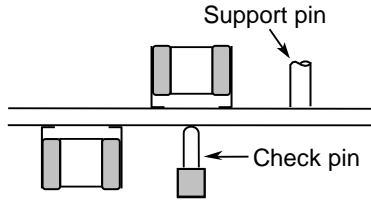
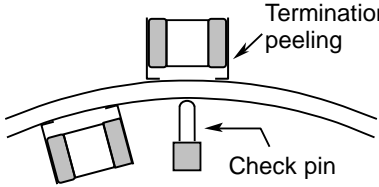
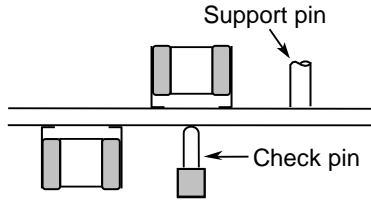
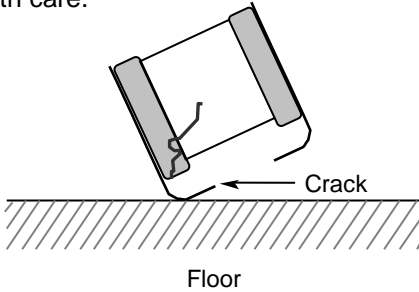
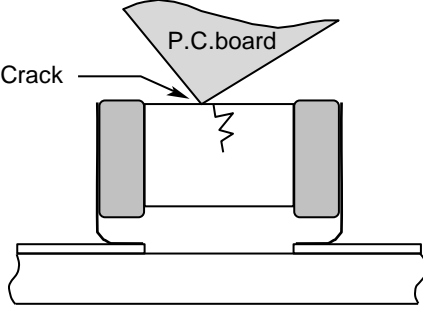



No.	Process	Condition															
5	Soldering	<div>5-1. Flux selection</div> <div>Flux can seriously affect the performance of capacitors. Confirm the following to select the appropriate flux.</div> <div>1) It is recommended to use a mildly activated rosin flux ( less than 0.1wt% chlorine ). Strong flux is not recommended.</div> <div>2) Excessive flux must be avoided. Please provide proper amount of flux.</div> <div>3) When water-soluble flux is used, enough washing is necessary.</div> <div>5-2. Recommended Reflow soldering profile</div> <div>1) Soldering condition (Preheating temperature, soldering temperature and these times) is limited to reflow soldering method which is stipulated on the specification.</div> <div>2) Chips should be mounted, shortly after a solder is on a P.C.Board.</div> <div><div>Reflow soldering</div></div> <div>5-3. Recommended soldering peak temp and peak temp duration</div> <div>Pb free solder is recommended, but if Sn-37Pb must be used, refer to below.</div> <table><tr><th rowspan="2">Temp./Duration Solder</th><th colspan="2">Reflow soldering</th></tr><tr><th>Peak temp(°C)</th><th>Duration(sec.)</th></tr><tr><td>Lead Free Solder</td><td>260 max.</td><td>10 max.</td></tr><tr><td>Sn-Pb Solder</td><td>230 max.</td><td>20 max.</td></tr></table> <div>Recommended solder compositions</div> <div>Lead Free Solder : Sn-3.0Ag-0.5Cu</div> <div>5-4. Avoiding thermal shock</div> <div>1) Preheating condition</div> <table><tr><th>Soldering</th><th>Temp. (°C)</th></tr><tr><td>Reflow soldering</td><td><math>\Delta T \leq 130</math></td></tr></table> <div>2) Cooling condition</div> <div>Natural cooling using air is recommended. If the chips are dipped into a solvent for cleaning, the temperature difference (<math>\Delta T</math>) must be less than 100°C.</div>	Temp./Duration Solder	Reflow soldering		Peak temp(°C)	Duration(sec.)	Lead Free Solder	260 max.	10 max.	Sn-Pb Solder	230 max.	20 max.	Soldering	Temp. (°C)	Reflow soldering	$\Delta T \leq 130$
Temp./Duration Solder	Reflow soldering																
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Soldering	Temp. (°C)																
Reflow soldering	$\Delta T \leq 130$																

No.	Process	Condition
5	Soldering	<p>5-5. Amount of solder</p> <p>Excessive solder will induce higher tensile force in chip capacitor when temperature changes and it may result in chip cracking. In sufficient solder may detach the capacitor from the P.C.board.</p>
		<div>Excessive solder</div>  <div>Higher tensile force in chip capacitor to cause crack</div>
		<div>Adequate</div> 
		<div>Insufficient solder</div>  <div>Low robustness may cause contact failure or chip capacitor comes off the P.C.board.</div>
		<p>5-6. Sn-Zn solder</p> <p>Sn-Zn solder affects product reliability.</p> <p>Please contact TDK in advance when utilize Sn-Zn solder.</p>
		<p>5-7. Countermeasure for tombstone</p> <p>The misalignment between the mounted positions of the capacitors and the land patterns should be minimized. The tombstone phenomenon may occur especially the capacitors are mounted (in longitudinal direction) in the same direction of the reflow soldering.</p> <p>(Refer to JEITA RCR-2335C Annex A (Informative) Recommendations to prevent the tombstone phenomenon)</p>
		<p>5-8. Other notes related to soldering</p> <p>Do not reuse products that have been removed with a soldering iron.</p> <p>Also, mounting this product with a soldering iron is not guaranteed.</p>

No.	Process	Condition
6	Cleaning	<p>1) If an unsuitable cleaning fluid is used, flux residue or some foreign articles may stick to chip capacitor surface to deteriorate especially the insulation resistance.</p> <p>2) If cleaning condition is not suitable, it may damage the chip capacitor.</p> <p>2)-1. Insufficient washing</p> <p>(1) Terminal electrodes may corrode by Halogen in the flux.</p> <p>(2) Halogen in the flux may adhere on the surface of capacitor, and lower the insulation resistance.</p> <p>(3) Water soluble flux has higher tendency to have above mentioned problems (1) and (2).</p> <p>2)-2. Excessive washing</p> <p>When ultrasonic cleaning is used, excessively high ultrasonic energy output can affect the connection between the ceramic chip capacitor's body and the terminal electrode. To avoid this, following is the recommended condition.</p> <p>Power : 20W/ℓ max.</p> <p>Frequency : 40kHz max.</p> <p>Washing time : 5 minutes max.</p> <p>2)-3. If the cleaning fluid is contaminated, density of Halogen increases, and it may bring the same result as insufficient cleaning.</p>
7	Coating and molding of the P.C.board	<p>1) When the P.C.board is coated, please verify the quality influence on the product.</p> <p>2) Please verify carefully that there is no harmful decomposing or reaction gas emission during curing which may damage the chip capacitor.</p> <p>3) Please verify the curing temperature.</p>
8	Handling after chip mounted  Caution	<p>1) Please pay attention not to bend or distort the P.C.board after soldering in handling otherwise the chip capacitor may crack.</p> <div style="display: flex; justify-content: space-around; align-items: center;"> <div style="text-align: center;"> <p>Bend</p>  </div> <div style="text-align: center;"> <p>Twist</p>  </div> </div>

No.	Process	Condition															
8	Handling after chip mounted <div> Caution</div>	<div>2) Printed circuit board cropping should not be carried out by hand, but by using the proper tooling. Printed circuit board cropping should be carried out using a board cropping jig as shown in the following figure or a board cropping apparatus to prevent inducing mechanical stress on the board.</div> <div>(1)Example of a board cropping jig</div> <div>Recommended example: The board should be pushed from the back side, close to the cropping jig so that the board is not bent and the stress applied to the capacitor is compressive.</div> <div>Unrecommended example: If the pushing point is far from the cropping jig and the pushing direction is from the front side of the board, large tensile stress is applied to the capacitor, which may cause cracks.</div> <div><div><div>Outline of jig</div><div></div></div><div><table><tr><th>Recommended</th><th>Unrecommended</th></tr><tr><td></td><td></td></tr></table></div></div> <div>(2)Example of a board cropping machine</div> <div>An outline of a printed circuit board cropping machine is shown below. The top and bottom blades are aligned with one another along the lines with the V-grooves on printed circuit board when cropping the board.</div> <div>Unrecommended example: Misalignment of blade position between top and bottom, right and left, or front and rear blades may cause a crack in the capacitor.</div> <div><div><div>Outline of machine</div><div></div></div><div><div>Principle of operation</div><div></div></div><div><div>Cross-section diagram</div><div></div></div></div> <div><table><tr><th rowspan="2">Recommended</th><th colspan="3">Unrecommended</th></tr><tr><th>Top-bottom misalignment</th><th>Left-right misalignment</th><th>Front-rear misalignment</th></tr><tr><td><div><div>Top blade</div><div></div></div></td><td><div><div>Top blade</div><div></div></div></td><td><div><div>Top blade</div><div></div></div></td><td><div><div>Top blade</div><div></div></div></td></tr></table></div>	Recommended	Unrecommended			Recommended	Unrecommended			Top-bottom misalignment	Left-right misalignment	Front-rear misalignment	<div><div>Top blade</div><div></div></div>	<div><div>Top blade</div><div></div></div>	<div><div>Top blade</div><div></div></div>	<div><div>Top blade</div><div></div></div>
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No.	Process	Condition						
8	Handling after chip mounted  Caution	<p>3) When functional check of the P.C.board is performed, check pin pressure tends to be adjusted higher for fear of loose contact. But if the pressure is excessive and bend the P.C.board, it may crack the chip capacitor or peel the terminations off. Please adjust the check pins not to bend the P.C.board.</p> <table border="1" data-bbox="459 353 1455 763"> <thead> <tr> <th data-bbox="459 353 616 421">Item</th><th data-bbox="616 353 1034 421">Not recommended</th><th data-bbox="1034 353 1455 421">Recommended</th></tr> </thead> <tbody> <tr> <td data-bbox="459 421 616 763">Board bending</td><td data-bbox="616 421 1034 763">  </td><td data-bbox="1034 421 1455 763">  </td></tr> </tbody> </table>	Item	Not recommended	Recommended	Board bending		
Item	Not recommended	Recommended						
Board bending								
9	Handling of loose chip capacitor	<p>1) If dropped the chip capacitor may crack. Once dropped do not use it. Especially, the large case sized chip capacitor is tendency to have cracks easily, so please handle with care.</p>  <p>2) Piling the P.C.board after mounting for storage or handling, the corner of the P.C. board may hit the chip capacitor of another board to cause crack.</p> 						
10	Estimated life and estimated failure rate of capacitors	<p>As per the estimated life and the estimated failure rate depend on the temperature and the voltage. This can be calculated by the equation described in JEITA RCR-2335C Annex F (Informative) Calculation of the estimated lifetime and the estimated failure rate ( Voltage acceleration coefficient : 3 multiplication rule, Temperature acceleration coefficient : 10°C rule)          The failure rate can be decreased by reducing the temperature and the voltage but they will not be guaranteed.</p>						

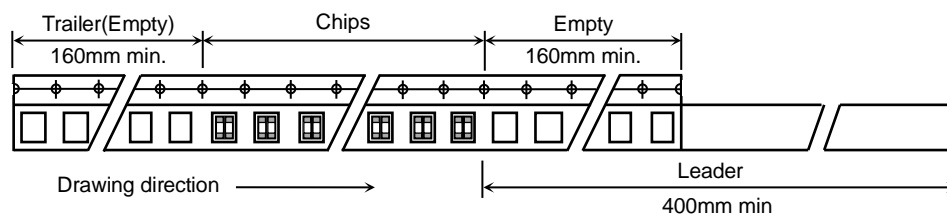
No.	Process	Condition
13	Caution during operation of equipment	<p>1) A capacitor shall not be touched directly with bare hands during operation in order to avoid electric shock. Electric energy held by the capacitor may be discharged through the human body when touched with a bare hand. Even when the equipment is off, a capacitor may stay charged. The capacitor should be handled after being completely discharged using a resistor.</p> <p>2) The terminals of a capacitor shall not be short-circuited by any accidental contact with a conductive object. A capacitor shall not be exposed to a conductive liquid such as an acid or alkali solution. A conductive object or liquid, such as acid and alkali, between the terminals may lead to the breakdown of a capacitor due to short circuit</p> <p>3) Confirm that the environment to which the equipment will be exposed during transportation and operation meets the specified conditions. Do not to use the equipment in the following environments.</p> <p>(1) Environment where a capacitor is splattered with water or oil (2) Environment where a capacitor is exposed to direct sunlight (3) Environment where a capacitor is exposed to Ozone, ultraviolet rays or radiation (4) Environment where a capacitor exposed to corrosive gas(e.g. hydrogen sulfide, sulfur dioxide, chlorine. ammonia gas etc.) (5) Environment where a capacitor exposed to vibration or mechanical shock exceeding the specified limits. (6) Atmosphere change with causes condensation</p>
14	<p>Others</p>  Caution	<p>The product listed in this specification is intended for use in automotive applications under-normal operation and usage conditions.</p> <p>The product is not designed or warranted to meet the requirements of application listed below, whose performance and/or quality requires a more stringent level of safety or reliability, or whose failure, malfunction or defect could cause serious damage to society, person or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below or for any other use exceeding the range or conditions set forth in this specification sheet. If you intend to use the products in the applications listed below or if you have special requirements exceeding the range or conditions set forth in this specification, please contact us.</p> <p>(1) Aerospace/Aviation equipment (2) Transportation equipment (electric trains, ships etc.) (3) Medical equipment (Excepting Pharmaceutical Affairs Law classification Class1, 2) (4) Power-generation control equipment (5) Atomic energy-related equipment (6) Seabed equipment (7) Transportation control equipment (8) Public information-processing equipment (9) Military equipment (10) Electric heating apparatus, burning equipment (11) Disaster prevention/crime prevention equipment (12) Safety equipment (13) Other applications that are not considered general-purpose applications</p> <p>When designing your equipment even for general-purpose applications, you are kindly requested to take into consideration securing protection circuit/device or providing backup circuits in your equipment.</p> <p>In addition, although the product listed in this specification is intended for use in automotive applications as described above, it is not prohibited to use for general electronic equipment, whose performance and/or quality doesn't require a more stringent level of safety or reliability, or whose failure, malfunction or defect could not cause serious damage to society, person or property.</p> <p>Therefore, the description of this caution will be applied, when the product is used in general electronic equipment under a normal operation and usage conditions.</p>

## 11. TAPE PACKAGING SPECIFICATION

### 1. CONSTRUCTION AND DIMENSION OF TAPING

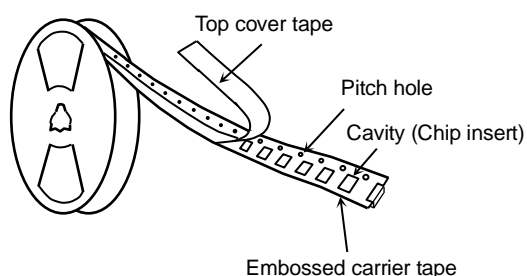
1-1. Dimensions of carrier tape  
According to Appendix 3.

1-2. Bulk part and leader of taping



1-3. Dimensions of reel  
According to Appendix 4.

1-4. Structure of taping



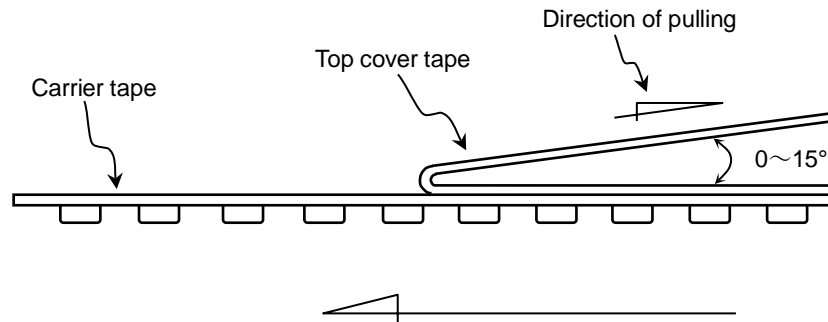
## 2. CHIP QUANTITY

Please refer to detail page on TDK web.

### 3. PERFORMANCE SPECIFICATIONS

#### 3-1. Fixing peeling strength (top cover tape)

$$0.05\text{N} < \text{Peeling strength} < 0.7\text{N}$$



3-2. Carrier tape shall be flexible enough to be wound around a minimum radius of 30mm with components in tape.

3-3. The missing of components shall be less than 0.1%

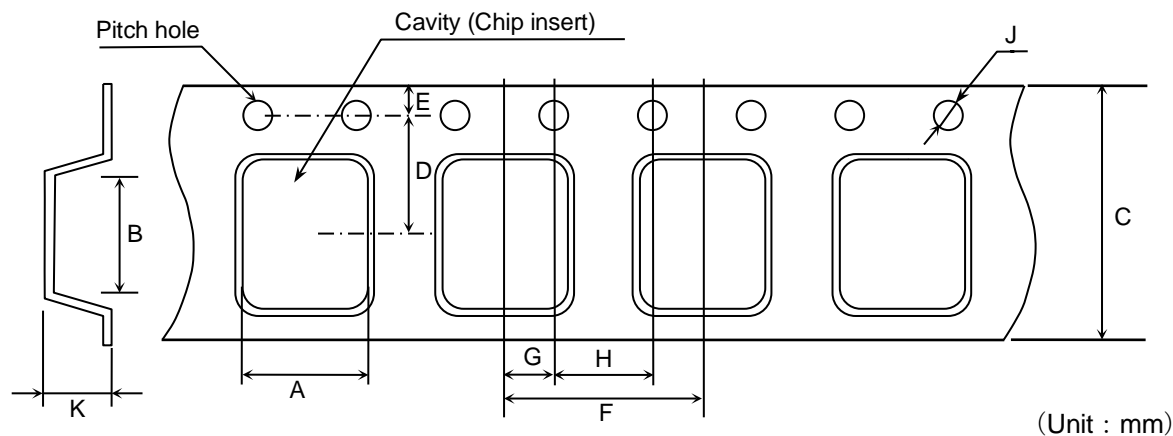
3-4. Components shall not stick to fixing tape.

3-5. When removing the cover tape, there shall not be difficulties by unfitting clearance gap, burrs and crushes of cavities. Also the sprocket holes shall not be covered by absorbing dust into the suction nozzle.



### Appendix 3

#### Plastic Tape



(Unit : mm)

Symbol Type	A	B	C	D	E	F
CAA572	(5.90)	(6.40)	16.0±0.30	7.50±0.10	1.75±0.10	12.00±0.10
CAA573	(6.40)	(8.70)				

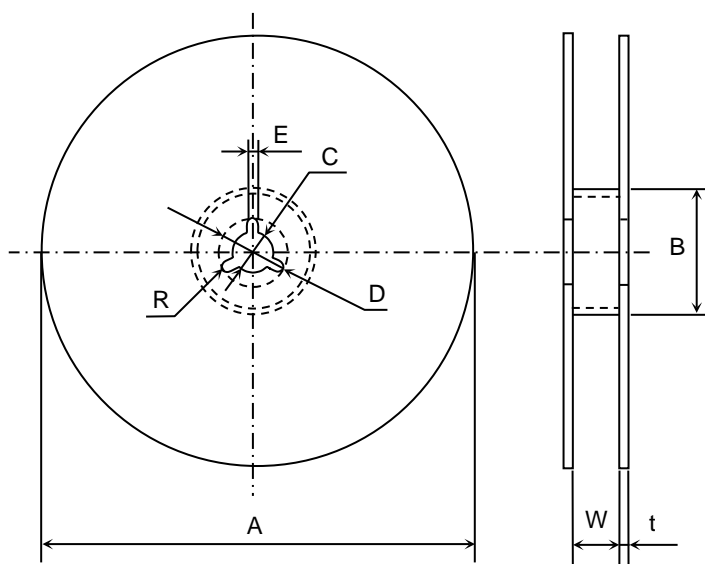
  

Symbol Type	G	H	J	K
CAA572	2.00±0.10	4.00±0.10	$\varnothing 1.50^{+0.1}_0$	6.80 max.
CAA573				

( ) Referenced value.

### Appendix 4

(Material : Polystyrene)



(Unit : mm)

Symbol	A	B	C	D	E	W
Dimension	$\varnothing 382$ max. (Nominal $\varnothing 330$ )	$\varnothing 50$ min.	$\varnothing 13 \pm 0.5$	$\varnothing 21 \pm 0.8$	$2.0 \pm 0.5$	$17.5 \pm 1.5$

Symbol	t	R
Dimension	$2.0 \pm 0.5$	1.0